Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Title::	Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages
Attorney Docket Number::	CPAC 1017-5 D3
Total Drawing Sheets::	7
Small Entity?::	No

Applicant Information

Applicant Authority Type:	Inventor
Primary Citizenship Country:	US
Status:	Full Capacity
Given Name:	Marcos
Family Name:	Karnezos
City of Residence:	Palo Alto
State or Province of Residence:	CA
Country of Residence:	US
Street of mailing address:	535 Lytton Avenue
City of mailing address:	Palo Alto
State or Province of mailing address:	CA
Country of mailing address:	US
Postal or Zip Code of mailing address:	94301

Correspondence Information

Correspondence Customer Number::   22470

Representative Information

Representative Customer Number::	22470	

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119 (e)	60411590	17 September 2002

Assignee Information

Assignee name::   ChipPAC, Inc.

Street of mailing address::   47400 Kato Road

City of mailing address::   Fremont

State or Province of mailing address::   CA

Country of mailing address::   US

Postal or Zip Code of mailing address:: 94538